

## CURRENT SHUNT MONITORS

### –16-V to +80-V Common-Mode Range

#### FEATURES

- Qualified for Automotive Applications
- Wide Common-Mode Voltage:  
–16 V to +80 V
- Low Error: 3.0% Over Temperature (Max)
- Bandwidth: Up to 500 kHz
- Three Transfer Functions Available:  
20 V/V, 50 V/V, and 100 V/V
- Complete Current-Sense Solution

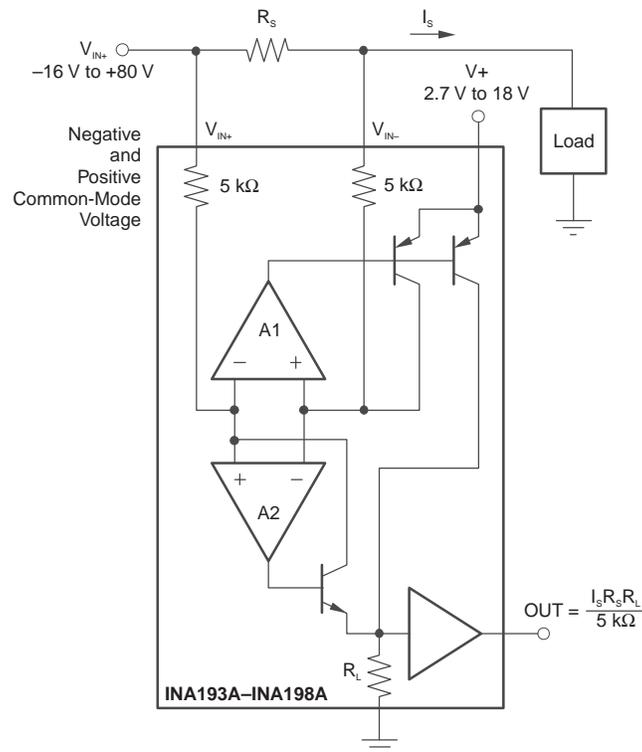
#### APPLICATIONS

- Welding Equipment
- Notebook Computers
- Cell Phones
- Telecom Equipment
- Automotive
- Power Management
- Battery Chargers

#### DESCRIPTION

The INA193A–INA198A family of current shunt monitors with voltage output can sense drops across shunts at common-mode voltages from –16 V to +80 V, independent of the INA19xA supply voltage. They are available with three output voltage scales: 20 V/V, 50 V/V, and 100 V/V. The 500-kHz bandwidth simplifies use in current control loops. The INA193A–INA195A provide identical functions but alternative pin configurations to the INA196A–INA198A, respectively.

The INA193A–INA198A operate from a single 2.7-V to 18-V supply. They are specified over the extended operating temperature range (–40°C to 125°C), and are offered in a space-saving SOT-23 package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

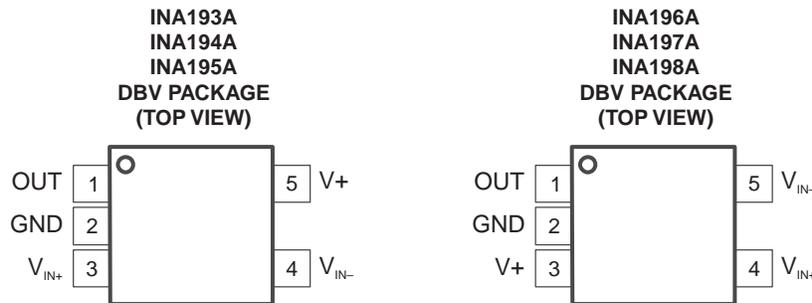
ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### ORDERING INFORMATION<sup>(1)</sup>

T <sub>A</sub>	PACKAGE <sup>(2)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 125°C	SOT-23 – DBV	Reel of 3000	INA193AQDBVRQ1	BOG
			INA194AQDBVRQ1	BOH
			INA195AQDBVRQ1	BOI
			INA196AQDBVRQ1	BOJ
			INA197AQDBVRQ1	BOK
			INA198AQDBVRQ1	BOL

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the website at [www.ti.com](http://www.ti.com).

(2) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



### ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

	MIN	MAX	UNIT
Supply voltage		18	V
Differential input voltage range, analog inputs (V <sub>IN+</sub> – V <sub>IN-</sub> )	–18	18	V
Common-mode voltage range <sup>(2)</sup>	–16	80	V
Analog output voltage range <sup>(2)</sup>	OUT	GND – 0.3 (V <sub>+</sub> ) + 0.3	V
Input current into any pin <sup>(2)</sup>		5	mA
Storage temperature range	–65	150	°C
Junction temperature		150	°C
ESD qualification ratings	Human-Body Model	4000	V
	Machine Model	200	
	Charged-Device Model	1000	

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) Input voltage at any pin may exceed the voltage shown if the current at that pin is limited to 5 mA.

## ELECTRICAL CHARACTERISTICS

 $V_S = 12\text{ V}$ ,  $V_{IN+} = 12\text{ V}$ ,  $V_{SENSE} = 100\text{ mV}$  (unless otherwise noted)

 Full range  $T_A = -40^\circ\text{C}$  to  $125^\circ\text{C}$ 

PARAMETER		TEST CONDITIONS	$T_A$	MIN	TYP	MAX	UNIT
<b>INPUT</b>							
$V_{SENSE}$	Full-scale input voltage	$V_{SENSE} = V_{IN+} - V_{IN-}$	$25^\circ\text{C}$		$0.15 \frac{(V_S - 0.2)}{\text{Gain}}$		V
VCM	Common-mode input		Full range	-16		80	V
CMR	Common-mode rejection	$V_{IN+} = -16\text{ V to }+80\text{ V}$	$25^\circ\text{C}$	80	94		dB
		$V_{IN+} = 12\text{ V to }80\text{ V}$	Full range	100	120		
$V_{OS}$	Offset voltage, RTI		$25^\circ\text{C}$		$\pm 0.5$	2	mV
			Full range		0.5	3	
$dV_{OS}/dT$	Offset voltage vs temperature		Full range		2.5		$\mu\text{V}/^\circ\text{C}$
PSR	Offset voltage vs power supply	$V_S = 2.7\text{ V to }18\text{ V}$ , $V_{IN+} = 18\text{ V}$	Full range		5	100	$\mu\text{V}/\text{V}$
$I_B$	Input bias current	$V_{IN-}$ pin	Full range		$\pm 8$	$\pm 23$	$\mu\text{A}$
<b>OUTPUT (<math>V_{SENSE} \geq 20\text{ mV}</math>)</b>							
G	Gain	INA193A, INA196A	$25^\circ\text{C}$	20		V/V	
		INA194A, INA197A		50			
		INA195A, INA198A		100			
	Gain error	$V_{SENSE} = 20\text{ mV to }100\text{ mV}$	$25^\circ\text{C}$	$\pm 0.2$	$\pm 1$	%	
			Full range		$\pm 2$		
	Total output error <sup>(1)</sup>		$25^\circ\text{C}$	$\pm 0.75$	$\pm 2.2$	%	
			Full range		$\pm 1$		$\pm 3$
	Nonlinearity error	$V_{SENSE} = 20\text{ mV to }100\text{ mV}$	$25^\circ\text{C}$	$\pm 0.002$	$\pm 0.1$	%	
$R_O$	Output impedance		$25^\circ\text{C}$	1.5		$\Omega$	
	Maximum capacitive load	No sustained oscillation	$25^\circ\text{C}$	10		nF	
<b>OUTPUT (<math>V_{SENSE} &lt; 20\text{ mV}</math>)<sup>(2)</sup></b>							
$V_{OUT}$	Output voltage	All devices	$25^\circ\text{C}$	$-16\text{ V} \leq V_{CM} < 0$	300		mV
				$V_S < V_{CM} \leq 80\text{ V}$	300		
		INA193A, INA196A		$0\text{ V} \leq V_{CM} \leq V_S$ , $V_S = 5\text{ V}$	0.4		V
		INA194A, INA197A			1		
INA195A, INA198A	2						
<b>VOLTAGE OUTPUT<sup>(3)</sup></b>							
	Swing to $V_+$ power-supply rail	$R_L = 100\text{ k}\Omega$ to GND	Full range	$V_+ - 0.1$	$V_+ - 0.2$	V	
	Swing to GND <sup>(4)</sup>	$R_L = 100\text{ k}\Omega$ to GND	Full range	$V_{GND} + 3$	$V_{GND} + 50$	mV	

(1) Total output error includes effects of gain error and  $V_{OS}$ .

(2) For details on this region of operation, see *Accuracy Variations as a Result of  $V_{SENSE}$  and Common-Mode Voltage in Applications Information*.

(3) See Typical Characteristics curve Output Swing vs Output Current.

(4) Specified by design

**ELECTRICAL CHARACTERISTICS (continued)**

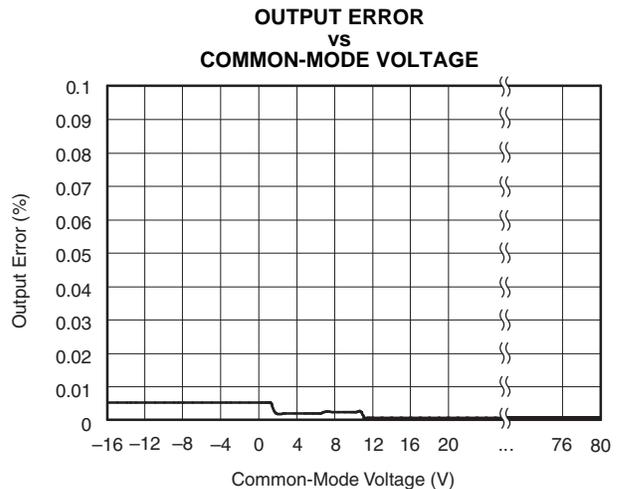
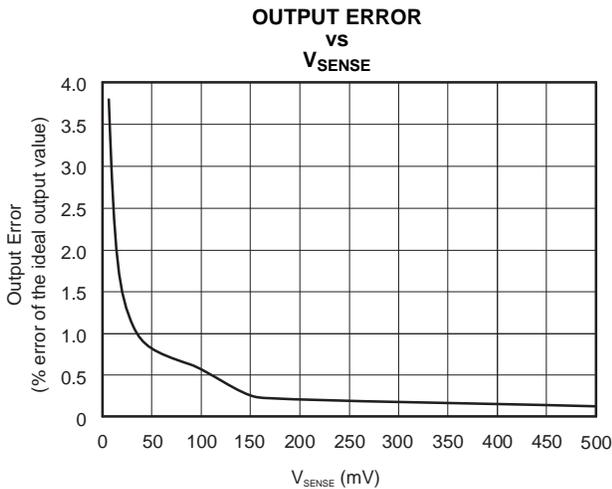
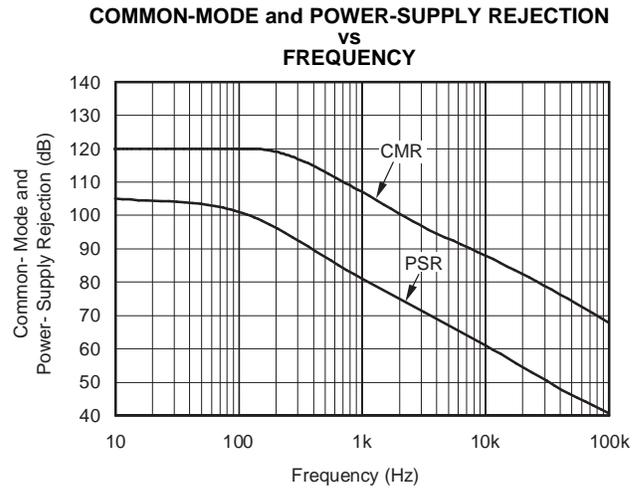
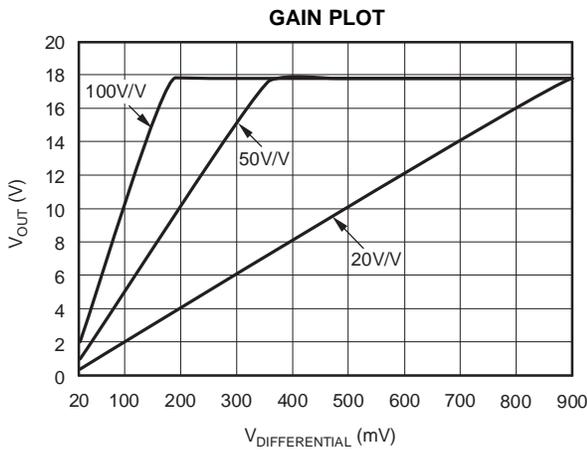
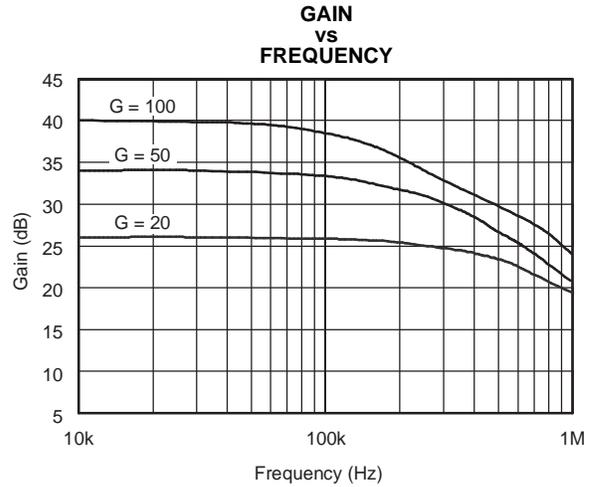
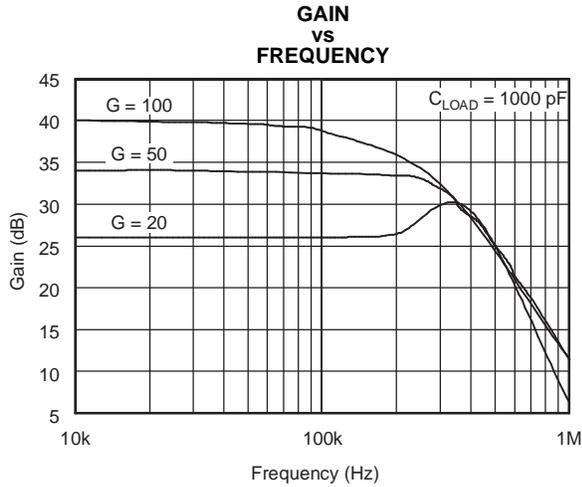
$V_S = 12\text{ V}$ ,  $V_{IN+} = 12\text{ V}$ ,  $V_{SENSE} = 100\text{ mV}$  (unless otherwise noted)

Full range  $T_A = -40^\circ\text{C}$  to  $125^\circ\text{C}$

PARAMETER		TEST CONDITIONS		$T_A$	MIN	TYP	MAX	UNIT
<b>FREQUENCY RESPONSE</b>								
BW	Bandwidth	INA193A, INA196A	$C_{LOAD} = 5\text{ pF}$	25°C	500		kHz	
		INA194A, INA197A			300			
		INA195A, INA198A			200			
	Phase margin	$C_{LOAD} < 10\text{ nF}$		25°C	40		°	
SR	Slew rate				1		V/μs	
$t_s$	Settling time (1%)	$V_{SENSE} = 10\text{ mV to }100\text{ mV}_{PP}$ , $C_{LOAD} = 5\text{ pF}$		25°C	2		μs	
<b>NOISE, RTI</b>								
	Voltage noise density			25°C	40		nV/√Hz	
<b>POWER SUPPLY</b>								
$V_S$	Operating voltage			Full range	2.7	18		V
$I_Q$	Quiescent current	$V_{OUT} = 2\text{ V}$		Full range	700		1250	μA
		INA193A, INA194A, INA196A, INA197A	$V_{SENSE} = 0\text{ mV}$	Full range	370		950	
		INA195A, INA198A			370		1050	
<b>TEMPERATURE RANGE</b>								
	Operating temperature				-40	125		°C
	Storage temperature				-65	150		°C
$\theta_{JA}$	Thermal resistance				200		°C/W	

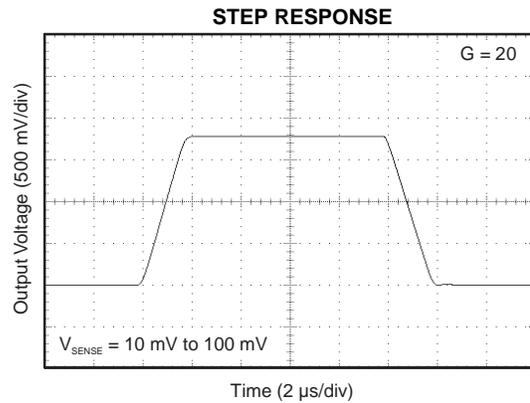
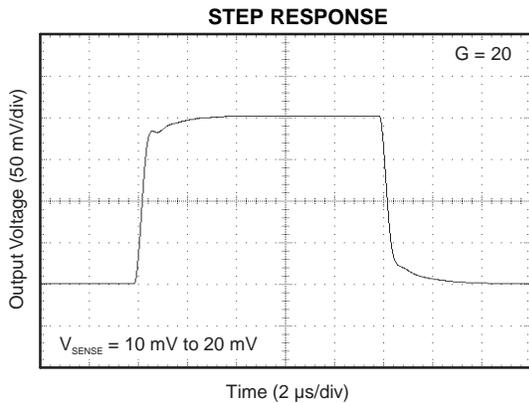
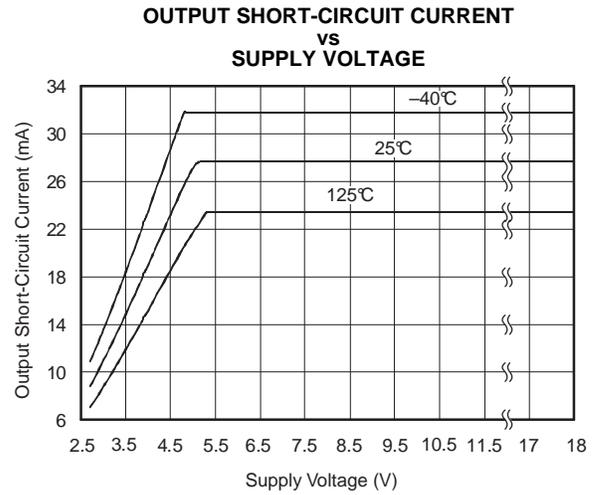
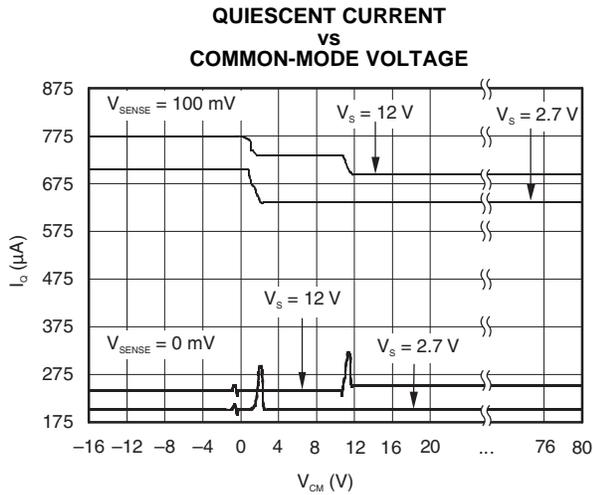
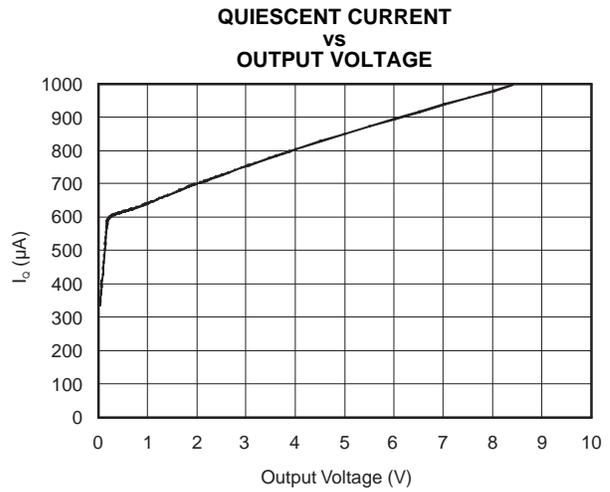
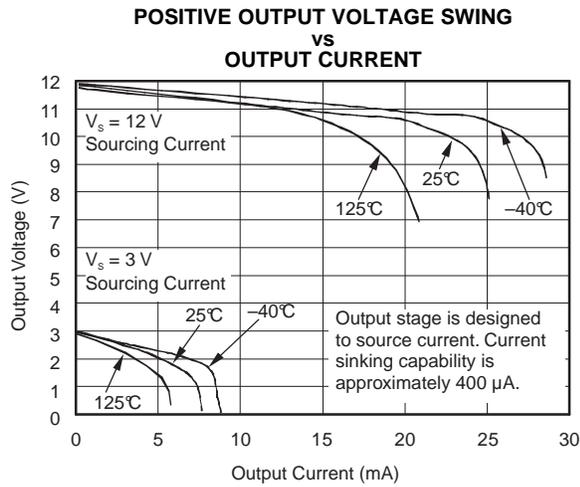
TYPICAL CHARACTERISTICS

$T_A = 25^\circ\text{C}$ ,  $V_S = 12\text{ V}$ ,  $V_{IN+} = 12\text{ V}$ , and  $V_{SENSE} = 100\text{ mV}$  (unless otherwise noted)



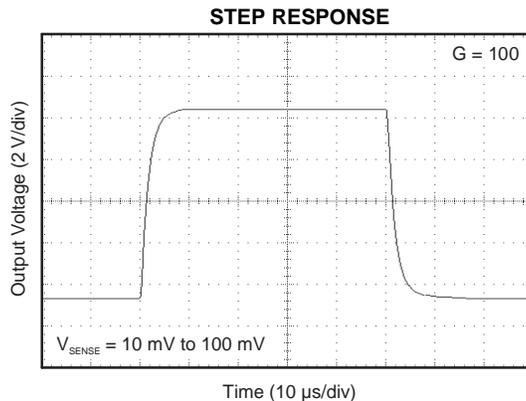
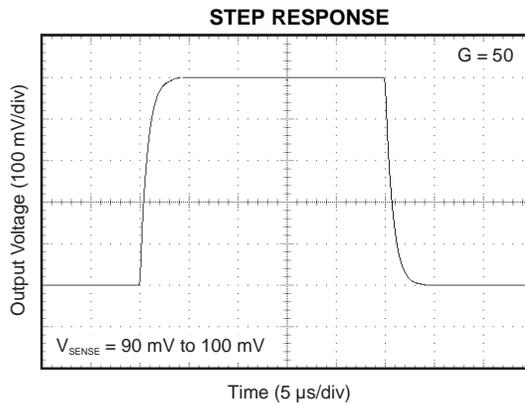
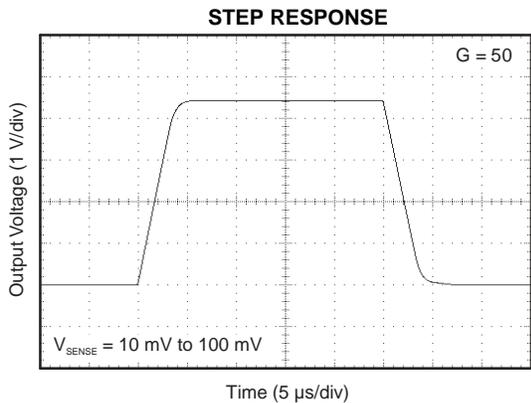
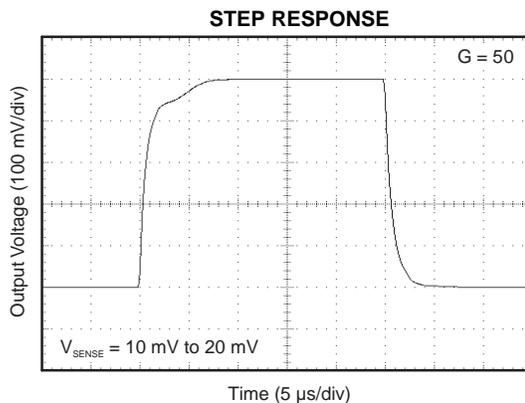
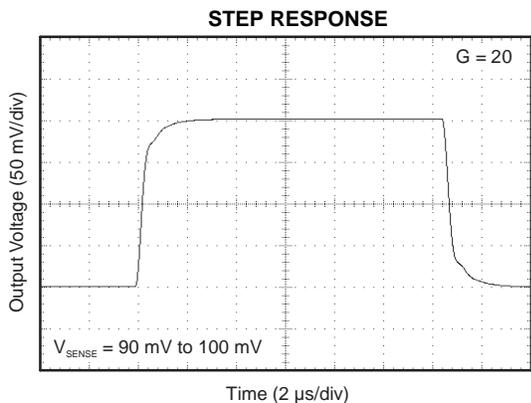
**TYPICAL CHARACTERISTICS (continued)**

$T_A = 25^\circ\text{C}$ ,  $V_S = 12\text{ V}$ ,  $V_{IN+} = 12\text{ V}$ , and  $V_{SENSE} = 100\text{ mV}$  (unless otherwise noted)



**TYPICAL CHARACTERISTICS (continued)**

$T_A = 25^\circ\text{C}$ ,  $V_S = 12\text{ V}$ ,  $V_{IN+} = 12\text{ V}$ , and  $V_{SENSE} = 100\text{ mV}$  (unless otherwise noted)



## APPLICATION INFORMATION

### Basic Connection

Figure 1 shows the basic connection of the INA19xA. The input pins,  $V_{IN+}$  and  $V_{IN-}$ , should be connected as closely as possible to the shunt resistor to minimize any resistance in series with the shunt resistance.

Power-supply bypass capacitors are required for stability. Applications with noisy or high-impedance power supplies may require additional decoupling capacitors to reject power-supply noise. Connect bypass capacitors close to the device pins.

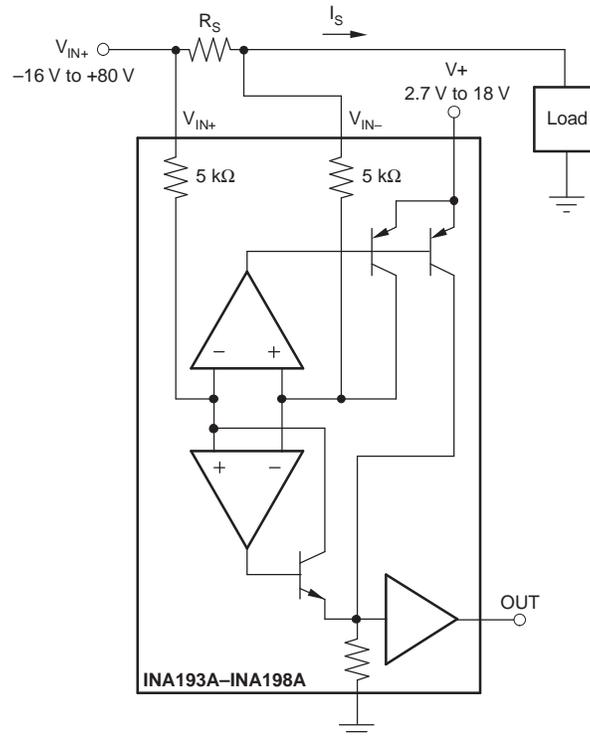


Figure 1. INA19xA Basic Connection

### Power Supply

The input circuitry of the INA19xA can accurately measure beyond its power-supply voltage,  $V_+$ . For example, the  $V_+$  power supply can be 5 V, whereas the load power-supply voltage is up to 80 V. The output voltage range of the OUT terminal, however, is limited by the voltages on the power-supply pin.

### Accuracy Variations as a Result of $V_{SENSE}$ and Common-Mode Voltage

The accuracy of the INA193A–INA198A current shunt monitors is a function of two main variables:  $V_{SENSE}$  ( $V_{IN+} - V_{IN-}$ ) and common-mode voltage,  $V_{CM}$ , relative to the supply voltage,  $V_S$ .  $V_{CM}$  is expressed as  $(V_{IN+} + V_{IN-})/2$ ; however, in practice,  $V_{CM}$  is seen as the voltage at  $V_{IN+}$  because the voltage drop across  $V_{SENSE}$  is usually small.

This section addresses the accuracy of these specific operating regions:

- Normal Case 1:  $V_{\text{SENSE}} \geq 20 \text{ mV}$ ,  $V_{\text{CM}} \geq V_{\text{S}}$   
 Normal Case 2:  $V_{\text{SENSE}} \geq 20 \text{ mV}$ ,  $V_{\text{CM}} < V_{\text{S}}$   
 Low  $V_{\text{SENSE}}$  Case 1:  $V_{\text{SENSE}} < 20 \text{ mV}$ ,  $-16 \text{ V} \leq V_{\text{CM}} < 0$   
 Low  $V_{\text{SENSE}}$  Case 2:  $V_{\text{SENSE}} < 20 \text{ mV}$ ,  $0 \text{ V} \leq V_{\text{CM}} \leq V_{\text{S}}$   
 Low  $V_{\text{SENSE}}$  Case 3:  $V_{\text{SENSE}} < 20 \text{ mV}$ ,  $V_{\text{S}} < V_{\text{CM}} \leq 80 \text{ V}$

### Normal Case 1: $V_{\text{SENSE}} \geq 20 \text{ mV}$ , $V_{\text{CM}} \geq V_{\text{S}}$

This region of operation provides the highest accuracy. Here, the input offset voltage is characterized and measured using a two-step method. First, the gain is determined by (Equation 1).

$$G = \frac{V_{\text{OUT1}} - V_{\text{OUT2}}}{100 \text{ mV} - 20 \text{ mV}} \quad (1)$$

Where:

$V_{\text{OUT1}}$  = Output voltage with  $V_{\text{SENSE}} = 100 \text{ mV}$

$V_{\text{OUT2}}$  = Output voltage with  $V_{\text{SENSE}} = 20 \text{ mV}$

The offset voltage is then measured at  $V_{\text{SENSE}} = 100 \text{ mV}$  and referred to the input (RTI) of the current shunt monitor, as shown in (Equation 2).

$$V_{\text{OSRTI}} (\text{Referred-To-Input}) = \left( \frac{V_{\text{OUT1}}}{G} \right) - 100 \text{ mV} \quad (2)$$

In the Typical Characteristics, the *Output Error vs Common-Mode Voltage* curve shows the highest accuracy for the this region of operation. In this plot,  $V_{\text{S}} = 12 \text{ V}$ ; for  $V_{\text{CM}} \geq 12 \text{ V}$ , the output error is at its minimum. This case is also used to create the  $V_{\text{SENSE}} \geq 20 \text{ mV}$  output specifications in the Electrical Characteristics table.

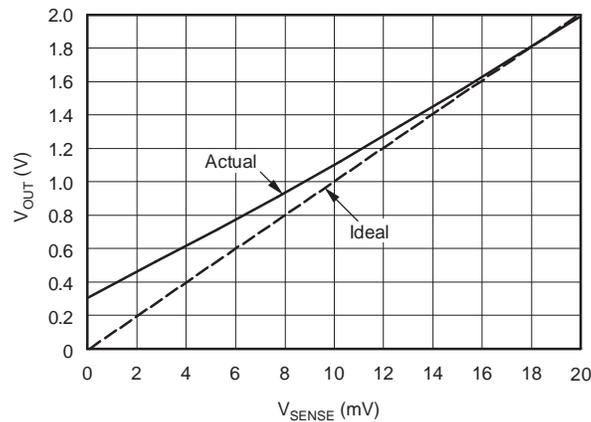
### Normal Case 2: $V_{\text{SENSE}} \geq 20 \text{ mV}$ , $V_{\text{CM}} < V_{\text{S}}$

This region of operation has slightly less accuracy than Normal Case 1 as a result of the common-mode operating area in which the part functions, as seen in the *Output Error vs Common-Mode Voltage* curve. As noted, for this graph  $V_{\text{S}} = 12 \text{ V}$ ; for  $V_{\text{CM}} < 12 \text{ V}$ , the Output Error increases as  $V_{\text{CM}}$  becomes less than 12 V, with a typical maximum error of 0.005% at the most negative  $V_{\text{CM}} = -16 \text{ V}$ .

### Low $V_{\text{SENSE}}$ Case 1: $V_{\text{SENSE}} < 20 \text{ mV}$ , $-16 \text{ V} \leq V_{\text{CM}} < 0$ ; and Low $V_{\text{SENSE}}$ Case 3: $V_{\text{SENSE}} < 20 \text{ mV}$ , $V_{\text{S}} < V_{\text{CM}} \leq 80 \text{ V}$

Although the INA193A–INA198A family of devices are not designed for accurate operation in either of these regions, some applications are exposed to these conditions; for example, when monitoring power supplies that are switched on and off while  $V_{\text{S}}$  is still applied to the INA193A–INA198A. It is important to know what the behavior of the devices will be in these regions.

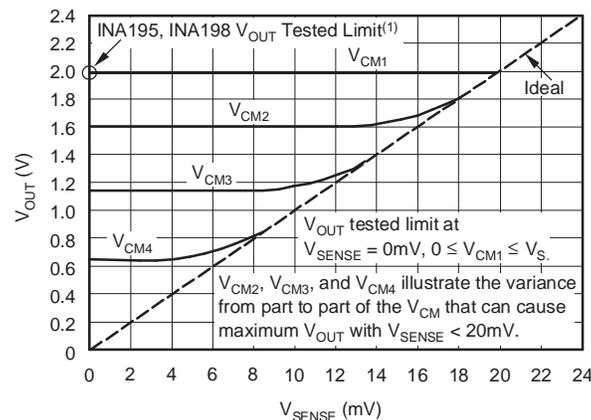
As  $V_{\text{SENSE}}$  approaches 0 mV, in these  $V_{\text{CM}}$  regions, the device output accuracy degrades. A larger-than-normal offset can appear at the current shunt monitor output with a typical maximum value of  $V_{\text{OUT}} = 300 \text{ mV}$  for  $V_{\text{SENSE}} = 0 \text{ mV}$ . As  $V_{\text{SENSE}}$  approaches 20 mV,  $V_{\text{OUT}}$  returns to the expected output value with accuracy as specified in the Electrical Characteristics. Figure 2 illustrates this effect using the INA195A and INA198A (Gain = 100).



**Figure 2. Example for Low  $V_{SENSE}$  Cases 1 and 3 (INA195A, INA198A: Gain = 100)**

**Low  $V_{SENSE}$  Case 2:  $V_{SENSE} < 20$  mV,  $0$  V  $\leq V_{CM} \leq V_S$**

This region of operation is the least accurate for the INA193A–INA198A family. To achieve the wide input common-mode voltage range, these devices use two op amp front ends in parallel. One op amp front end operates in the positive input common-mode voltage range, and the other in the negative input region. For this case, neither of these two internal amplifiers dominates and overall loop gain is very low. Within this region,  $V_{OUT}$  approaches voltages close to linear operation levels for Normal Case 2. This deviation from linear operation becomes greatest the closer  $V_{SENSE}$  approaches 0 V. Within this region, as  $V_{SENSE}$  approaches 20 mV, device operation is closer to that described by Normal Case 2. Figure 3 illustrates this behavior for the INA195A. The  $V_{OUT}$  maximum peak for this case is tested by maintaining a constant  $V_S$ , setting  $V_{SENSE} = 0$  mV and sweeping  $V_{CM}$  from 0 V to  $V_S$ . The exact  $V_{CM}$  at which  $V_{OUT}$  peaks during this test varies from part to part, but the  $V_{OUT}$  maximum peak is tested to be less than the specified  $V_{OUT}$  tested limit.

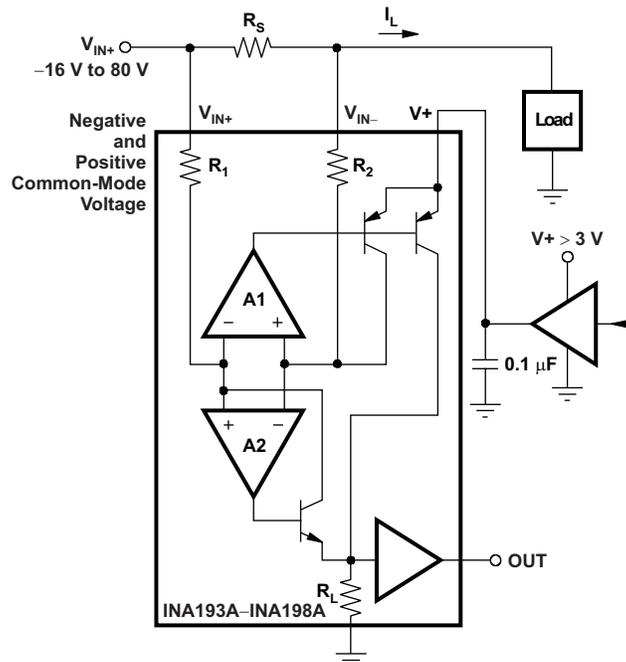


NOTE: (1) INA193, INA196  $V_{OUT}$  Tested Limit = 0.4V.  
 INA194, INA197  $V_{OUT}$  Tested Limit = 1V.

**Figure 3. Example for Low  $V_{SENSE}$  Case 2 (INA195A, INA198A: Gain = 100)**

## Shutdown

Because the INA193A–INA198A consume a quiescent current less than 1 mA, they can be powered by either the output of logic gates or by transistor switches to supply power. Use a totem pole output buffer or gate that can provide sufficient drive along with 0.1  $\mu\text{F}$  bypass capacitor, preferably ceramic with good high frequency characteristics. This gate should have a supply voltage of 3 V or greater because the INA193A–INA198A requires a minimum supply greater than 2.7 V. In addition to eliminating quiescent current, this gate also turns off the 10  $\mu\text{A}$  bias current present at each of the inputs. An example shutdown circuit is shown in Figure 4.



**Figure 4. INA193A–INA198A Example Shutdown Circuit**

## Selecting $R_S$

The value chosen for the shunt resistor,  $R_S$ , depends on the application and is a compromise between small-signal accuracy and maximum permissible voltage loss in the measurement line. High values of  $R_S$  provide better accuracy at lower currents by minimizing the effects of offset, while low values of  $R_S$  minimize voltage loss in the supply line. For most applications, best performance is attained with an  $R_S$  value that provides a full-scale shunt voltage range of 50 mV to 100 mV. Maximum input voltage for accurate measurements is 500 mV.

## Transient Protection

The –16-V to +80-V common-mode range of the INA19xA is ideal for withstanding automotive fault conditions ranging from 12 V battery reversal up to 80-V transients, since no additional protective components are needed up to those levels. In the event that the INA19xA is exposed to transients on the inputs in excess of its ratings, then external transient absorption with semiconductor transient absorbers (zeners or Transzorbs) are necessary. Use of MOVs or VDRs is not recommended except when they are used in addition to a semiconductor transient absorber. Select the transient absorber such that it never allows the INA19xA to be exposed to transients greater than 80 V (that is, allow for transient absorber tolerance, as well as additional voltage due to transient absorber dynamic impedance). Despite the use of internal zener-type ESD protection, the INA19xA does not lend itself to using external resistors in series with the inputs since the internal gain resistors can vary up to  $\pm 30\%$ . (If gain accuracy is not important, then resistors can be added in series with the INA19xA inputs with two equal resistors on each input.)

## Output Voltage Range

The output of the INA19xA is accurate within the output voltage swing range set by the power supply pin, V+. This is best illustrated when using the INA195A or INA198A (which are both versions using a gain of 100), where a 100-mV full-scale input from the shunt resistor requires an output voltage swing of 10 V, and a power-supply voltage sufficient to achieve 10 V on the output.

## RFI/EMI

Attention to good layout practices is always recommended. Keep traces short and, when possible, use a printed circuit board (PCB) ground plane with surface-mount components placed as close to the device pins as possible. Small ceramic capacitors placed directly across amplifier inputs can reduce RFI/EMI sensitivity. PCB layout should locate the amplifier as far away as possible from RFI sources. Sources can include other components in the same system as the amplifier itself, such as inductors (particularly switched inductors handling a lot of current and at high frequencies). RFI can generally be identified as a variation in offset voltage or dc signal levels with changes in the interfering RF signal. If the amplifier cannot be located away from sources of radiation, shielding may be needed. Twisting wire input leads makes them more resistant to RF fields. The difference in input pin location of the INA193A–INA195A versus the INA196A–INA198A may provide different EMI performance.

## Input Filtering

An obvious and straightforward location for filtering is at the output of the INA19xA series; however, this location negates the advantage of the low output impedance of the internal buffer. The only other option for filtering is at the input pins of the INA19xA, which is complicated by the internal 5-k $\Omega$   $\pm$  30% input impedance (see [Figure 5](#)). Using the lowest possible resistor values minimizes both the initial shift in gain and effects of tolerance. The effect on initial gain is given by:

$$\text{Gain Error \%} = 100 - \left( 100 \times \frac{5 \text{ k}\Omega}{5 \text{ k}\Omega + R_{\text{FILT}}} \right) \quad (3)$$

Total effect on gain error can be calculated by replacing the 5-k $\Omega$  term with 5 k $\Omega$  – 30% (or 3.5 k $\Omega$ ) or 5 k $\Omega$  + 30% (or 6.5 k $\Omega$ ). The tolerance extremes of R<sub>FILT</sub> can also be inserted into the equation. If a pair of 100- $\Omega$  1% resistors are used on the inputs, the initial gain error is 1.96%. Worst-case tolerance conditions always occur at the lower excursion of the internal 5-k $\Omega$  resistor (3.5 k $\Omega$ ), and the higher excursion of R<sub>FILT</sub>, 3% in this case.

Note that the specified accuracy of the INA19xA must then be combined in addition to these tolerances. While this discussion treats accuracy worst-case conditions by combining the extremes of the resistor values, it is appropriate to use geometric mean or root sum square calculations to total the effects of accuracy variations.

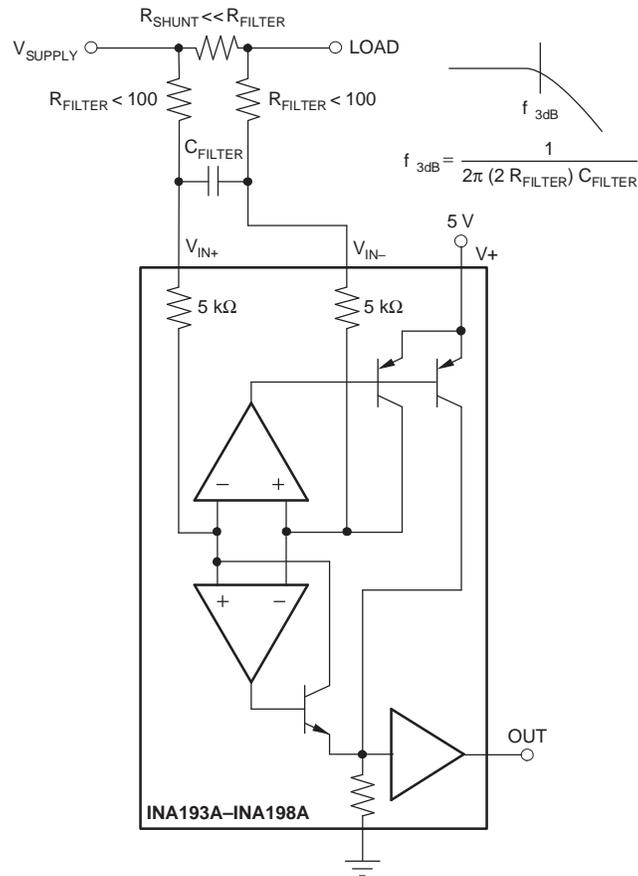


Figure 5. Input Filter (Gain Error = 1.5% to –2.2%)

## Inside the INA19xA

The INA19xA uses a new, unique, internal circuit topology that provides common-mode range extending from  $-16\text{ V}$  to  $+80\text{ V}$  while operating from a single power supply. The common-mode rejection in a classic instrumentation amplifier approach is limited by the requirement for accurate resistor matching. By converting the induced input voltage to a current, the INA19xA provides common-mode rejection that is no longer a function of closely matched resistor values, providing the enhanced performance necessary for such a wide common-mode range. A simplified diagram (see [Figure 6](#)) shows the basic circuit function. When the common-mode voltage is positive, amplifier A2 is active.

The differential input voltage,  $V_{IN+} - V_{IN-}$  applied across  $R_S$ , is converted to a current through a  $5\text{-k}\Omega$  resistor. This current is converted back to a voltage through  $R_L$ , and then amplified by the output buffer amplifier. When the common-mode voltage is negative, amplifier A1 is active. The differential input voltage,  $V_{IN+} - V_{IN-}$  applied across  $R_S$ , is converted to a current through a  $5\text{-k}\Omega$  resistor. This current is sourced from a precision current mirror whose output is directed into  $R_L$ , converting the signal back into a voltage and amplified by the output buffer amplifier. Patent-pending circuit architecture ensures smooth device operation, even during the transition period where both amplifiers A1 and A2 are active.

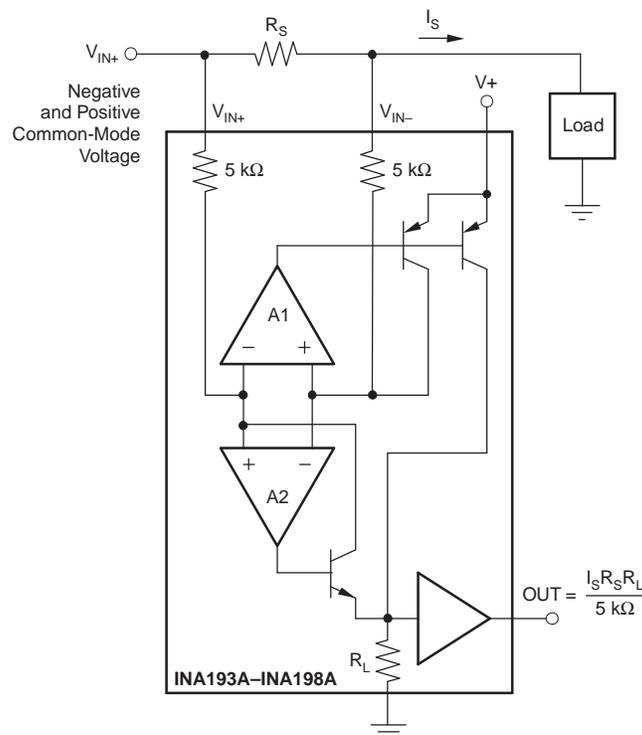


Figure 6. INA19xA Simplified Circuit Diagram

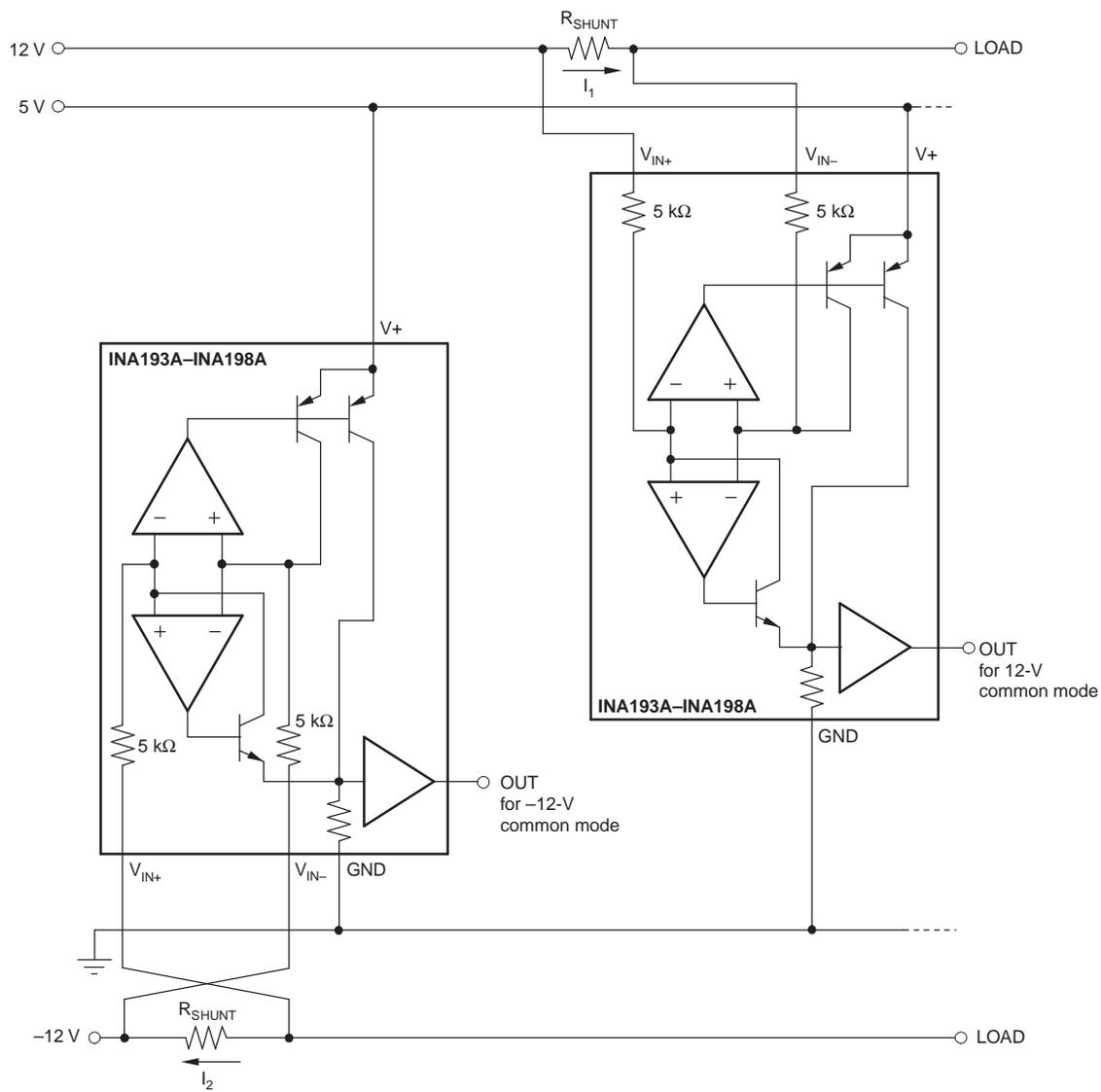


Figure 7. Monitor Bipolar Output Power-Supply Current

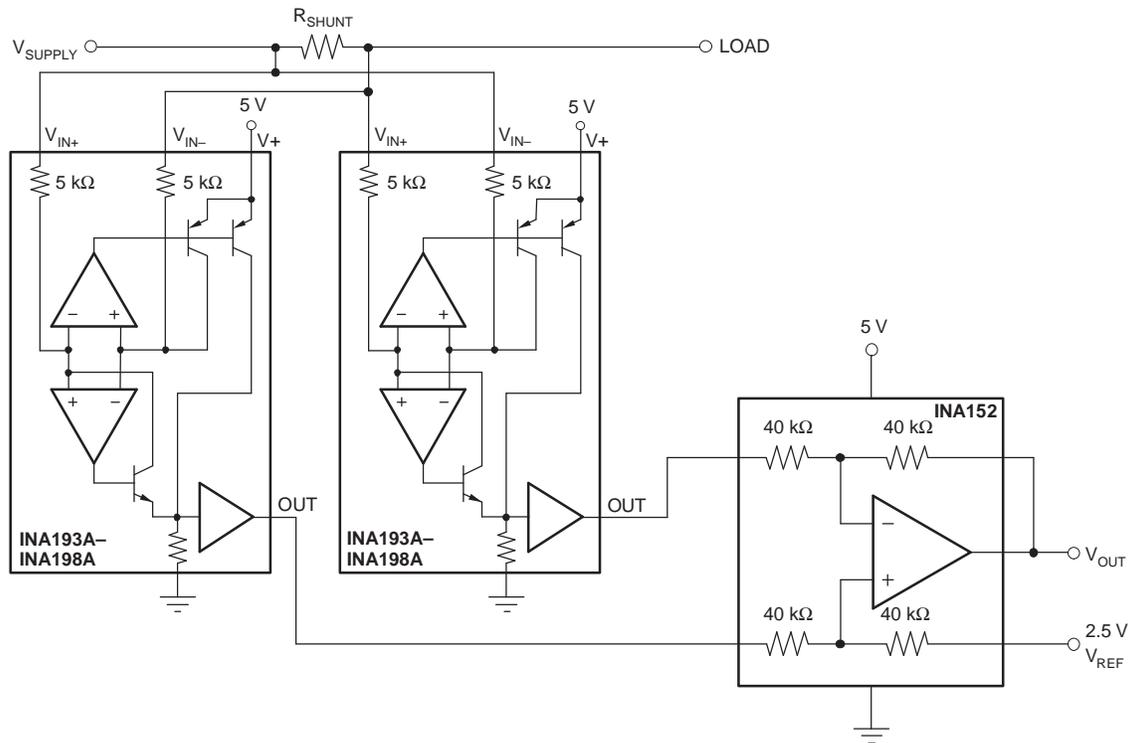


Figure 8. Bidirectional Current Monitoring

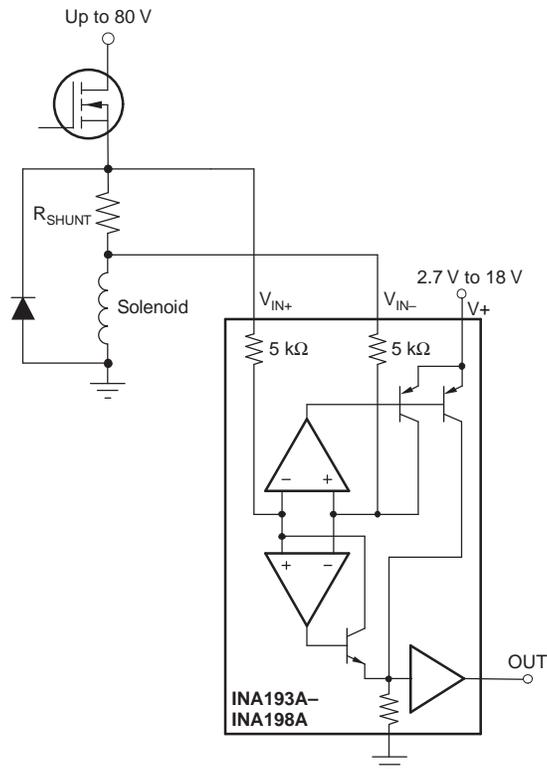
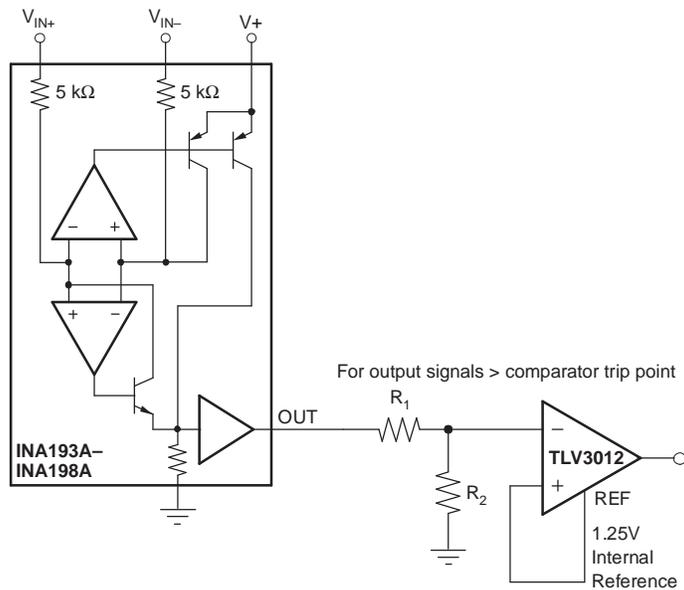
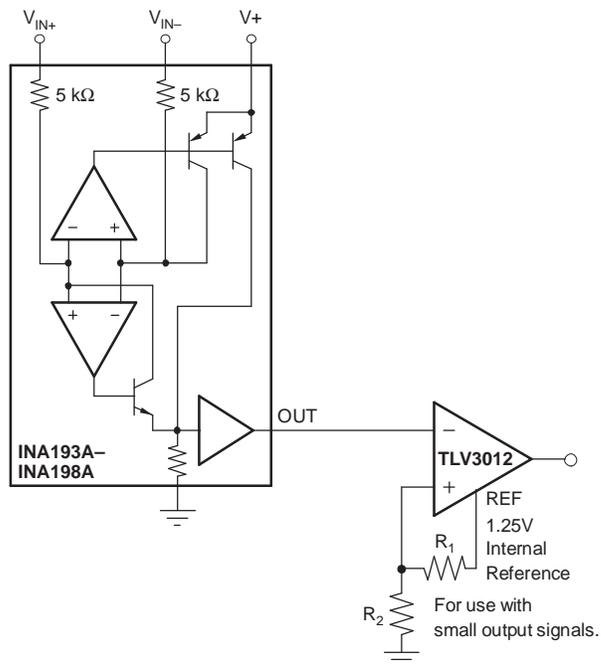


Figure 9. Inductive Current Monitor Including Flyback



(a) INA19xA Output Adjusted by Voltage Divider



(b) Comparator Reference Voltage Adjusted by Voltage Divider

**Figure 10. INA19xA With Comparator**

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
INA193AQDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	BOG	<a href="#">Samples</a>
INA194AQDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	BOH	<a href="#">Samples</a>
INA195AQDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	BOI	<a href="#">Samples</a>
INA196AQDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	BOJ	<a href="#">Samples</a>
INA197AQDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	BOK	<a href="#">Samples</a>
INA198AQDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	BOL	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

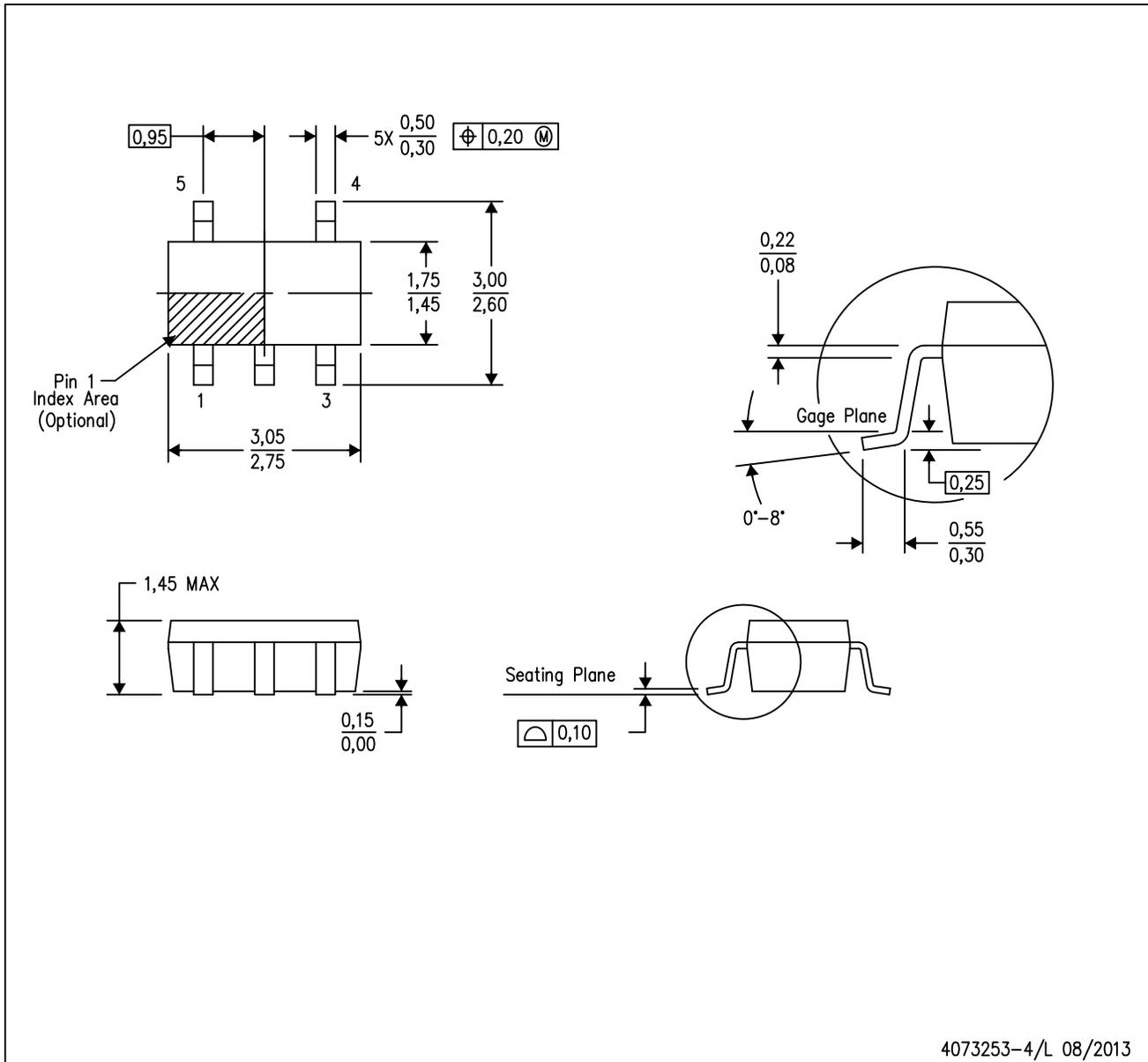
(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

DBV (R-PDSO-G5)

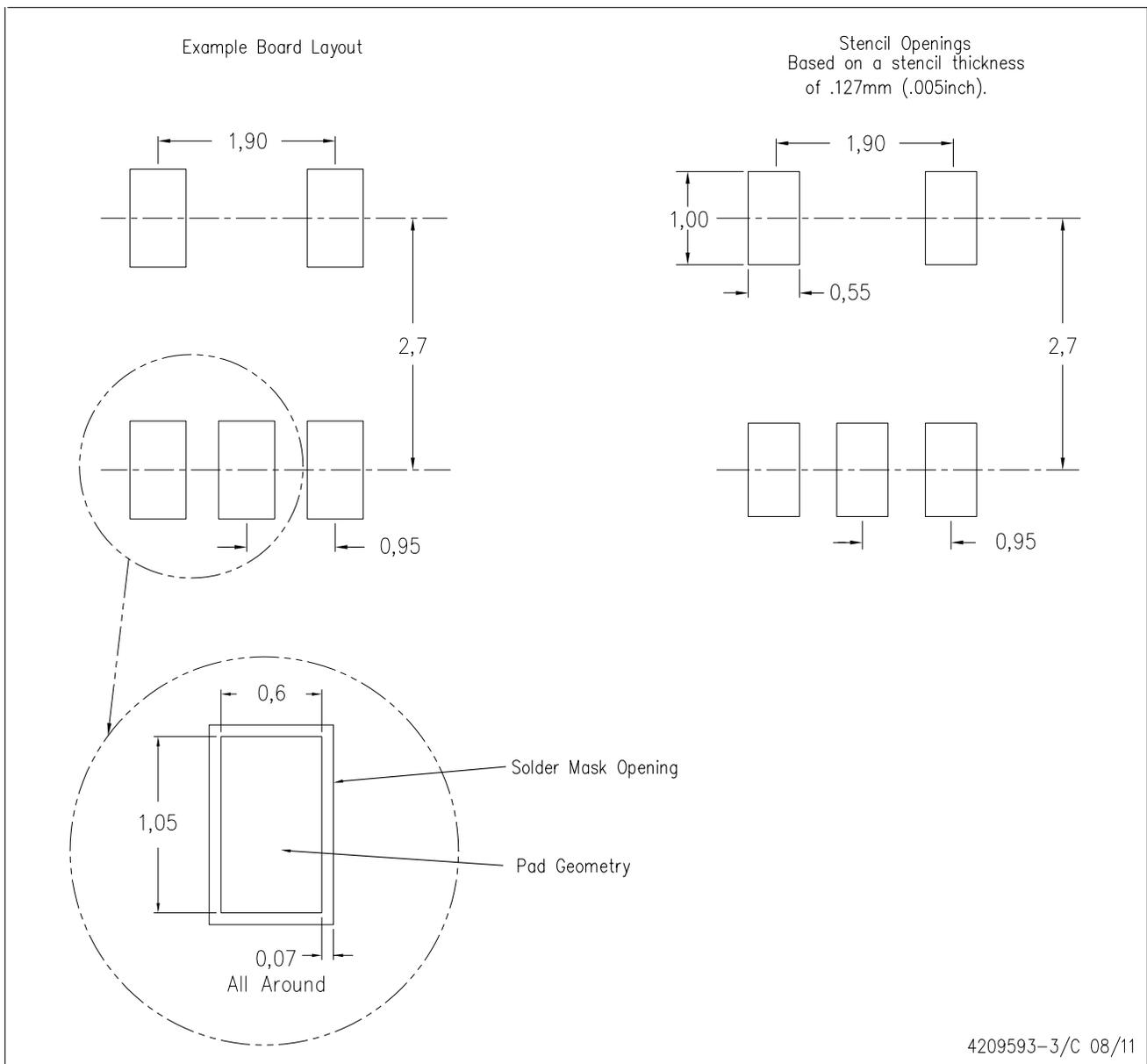
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - D. Falls within JEDEC MO-178 Variation AA.

DBV (R-PDSO-G5)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
  - D. Publication IPC-7351 is recommended for alternate designs.
  - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>

### TI E2E Community

[e2e.ti.com](http://e2e.ti.com)